

C4MV015065T

650V 15mΩ VGS Optimized Silicon Carbide Power MOSFET
N-Channel Enhancement Mode

Features

- Industry compatible drive voltage +15V..18V
- Industry standard Top Side Cooled (TSC) package
- High power dissipation capability
- Optimized package with separate driver source pin
- High-speed switching with low capacitances
- Soft body diode to minimize voltage overshoots
- Halogen free, RoHS compliant

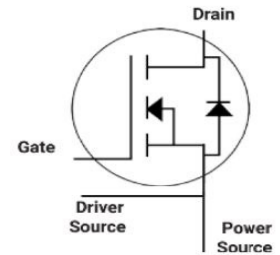
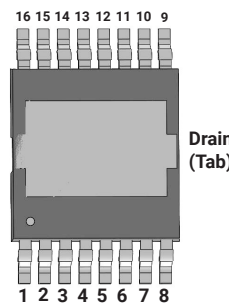
Benefits

- Compatible with industry standard gate drivers
- Increase power density
- Reduce cooling requirements
- Reduce switching losses and minimize gate ringing
- Higher system efficiency
- Increase system switching frequency

Applications

- EV Chargers
- Solar/ESS
- Motor Control
- Industrial Power Supplies
- High Voltage DC/DC Converters

Package



Orderable Part Number	Package	Marking
C4MV015065T-TR	TOLT (TSC)	C4MV015065T

Key Parameters

Parameter	Symbol	Min.	Typ.	Max	Unit	Conditions	Note
Drain - Source Voltage	V_{DS}			650	V	$T_c = 25^\circ\text{C}$	
Maximum Gate - Source Voltage	V_{GS}	-10		+23			Refer to PRD-04814
DC Continuous Drain Current	I_D		150		A	$V_{GS} = 18\text{ V}, T_c = 25^\circ\text{C}, T_J \leq 175^\circ\text{C}$	Fig 19 Note 1
			111			$V_{GS} = 18\text{ V}, T_c = 100^\circ\text{C}, T_J \leq 175^\circ\text{C}$	
Pulsed Drain Current	I_{DM}			390		t_{Pmax} limited by T_{Jmax} $V_{GS} = 18\text{ V}, T_c = 25^\circ\text{C}$	Fig 22
Power Dissipation	P_D		714		W	$T_c = 25^\circ\text{C}, T_J = 175^\circ\text{C}$	Fig 20
Operating Junction and Storage Temperature	T_J, T_{stg}	-55		175	$^\circ\text{C}$		
Solder Temperature	T_L			260		According to JEDEC J-STD-020	

Note (1): Verified by Design


Electrical Characteristics ($T_c = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions	Note
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	650				$V_{GS} = 0\text{ V}, I_D = 100\text{ }\mu\text{A}$	
$V_{GS(th)}$	Gate Threshold Voltage	1.8	2.6	3.8	V	$V_{DS} = V_{GS}, I_D = 15.32\text{ mA}$	Fig. 11
			2.2			$V_{DS} = V_{GS}, I_D = 15.32\text{ mA}, T_J = 175^\circ\text{C}$	
I_{DSS}	Zero Gate Voltage Drain Current		1	50	μA	$V_{DS} = 650\text{ V}, V_{GS} = 0\text{ V}$	
I_{GSS}	Gate-Source Leakage Current		10	250	nA	$V_{GS} = 18\text{ V}, V_{DS} = 0\text{ V}$	
$V_{GS(op)}$	Recommended Turn On Gate-Source Voltage		+15..+18		V		Refer to PRD-09634
	Recommended Turn Off Gate-Source Voltage		-5..0				
$R_{DS(on)}$	Drain-Source On-State Resistance		15	21	m Ω	$V_{GS} = 18\text{ V}, I_D = 55.72\text{ A}$	Fig. 4, 5, 6
			27			$V_{GS} = 18\text{ V}, I_D = 55.72\text{ A}, T_J = 175^\circ\text{C}$	
			18			$V_{GS} = 15\text{ V}, I_D = 55.72\text{ A}$	
g_{fs}	Transconductance		42		S	$V_{DS} = 20\text{ V}, I_{DS} = 55.72\text{ A}$	Fig. 7
			39			$V_{DS} = 20\text{ V}, I_{DS} = 55.72\text{ A}, T_J = 175^\circ\text{C}$	
C_{iss}	Input Capacitance		4488		pF	$V_{GS} = 0\text{ V}, V_{DS} = 0\text{ V to } 400\text{ V}$ $f = 100\text{ kHz}$ $V_{AC} = 25\text{ mV}$	Fig. 17, 18
C_{oss}	Output Capacitance		277				
C_{rss}	Reverse Transfer Capacitance		24				
E_{oss}	C_{oss} Stored Energy		28		μJ		Fig. 16
$C_{o(er)}$	Effective Output Capacitance (Energy Related)		362		pF	$V_{GS} = 0\text{ V}, V_{DS} = 0... 400\text{ V}$	Note: 3
$C_{o(tr)}$	Effective Output Capacitance (Time Related)		517				
E_{ON}	Turn-On Switching Energy (Diode FWD)		110		μJ	$V_{DS} = 400\text{ V}, V_{GS} = -4\text{ V}/18\text{ V}, I_D = 55.72\text{ A},$ $R_{G(ext)} = 2.5\text{ }\Omega, L = 59\text{ }\mu\text{H}, T_J = 175^\circ\text{C}$ FWD = Internal Body Diode	
E_{OFF}	Turn-Off Switching Energy (Diode FWD)		66				
$t_{d(on)}$	Turn-On Delay Time		16		ns	$V_{DD} = 400\text{ V}, V_{GS} = -4\text{ V}/18\text{ V}$ $I_D = 55.72\text{ A}, R_{G(ext)} = 2.5\text{ }\Omega,$ Timing relative to V_{DS} Inductive load	
t_r	Rise Time		7				
$t_{d(off)}$	Turn-Off Delay Time		41				
t_f	Fall Time		10				
$R_{G(int)}$	Internal Gate Resistance		1.5		Ω	$f = 1\text{ MHz}$	
Q_{gs}	Gate to Source Charge		46		nC	$V_{DS} = 400\text{ V}, V_{GS} = -4\text{ V}/18\text{ V}$ $I_D = 55.72\text{ A}$ Per IEC60747-8-4 pg 21	Fig. 12
Q_{gd}	Gate to Drain Charge		48				
Q_g	Total Gate Charge		178				

Note (3): $C_{o(er)}$, a lumped capacitance that gives same stored energy as C_{oss} while V_{ds} is rising from 0 to 400V

$C_{o(tr)}$, a lumped capacitance that gives same charging time as C_{oss} while V_{ds} is rising from 0 to 400V


Reverse Diode Characteristics ($T_c = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Typ.	Max.	Unit	Test Conditions	Note
V_{SD}	Diode Forward Voltage	4.9		V	$V_{GS} = -4\text{ V}, I_{SD} = 27.9\text{ A}, T_J = 25^\circ\text{C}$	Fig. 8, 9, 10
		4.4			$V_{GS} = -4\text{ V}, I_{SD} = 27.9\text{ A}, T_J = 175^\circ\text{C}$	
I_S	Continuous Diode Forward Current		100	A	$V_{GS} = -4\text{ V}, T_c = 25^\circ\text{C}$	
I_{SM}	Diode pulse Current		390		$V_{GS} = -4\text{ V}$, pulse width t_p limited by T_{Jmax}	
t_{rr}	Reverse Recovery time	14		ns	$V_{GS} = -4\text{ V}, I_{SD} = 55.72\text{ A}, V_R = 400\text{ V}$ $dif/dt = 11638\text{ A}/\mu\text{s}, T_J = 175^\circ\text{C}$	
Q_{rr}	Reverse Recovery Charge	934		nC		
I_{rrm}	Peak Reverse Recovery Current	106		A		
t_{rr}	Reverse Recovery time	48		ns	$V_{GS} = -4\text{ V}, I_{SD} = 55.72\text{ A}, V_R = 400\text{ V}$ $dif/dt = 2115\text{ A}/\mu\text{s}, T_J = 175^\circ\text{C}$	
Q_{rr}	Reverse Recovery Charge	327		nC		
I_{rrm}	Peak Reverse Recovery Current	23		A		

Thermal Characteristics

Symbol	Parameter	Typ.	Unit	Test Conditions	Note
$R_{\theta JC}$	Thermal Resistance from Junction to Case	0.21	$^\circ\text{C}/\text{W}$		Fig. 21



Typical Performance

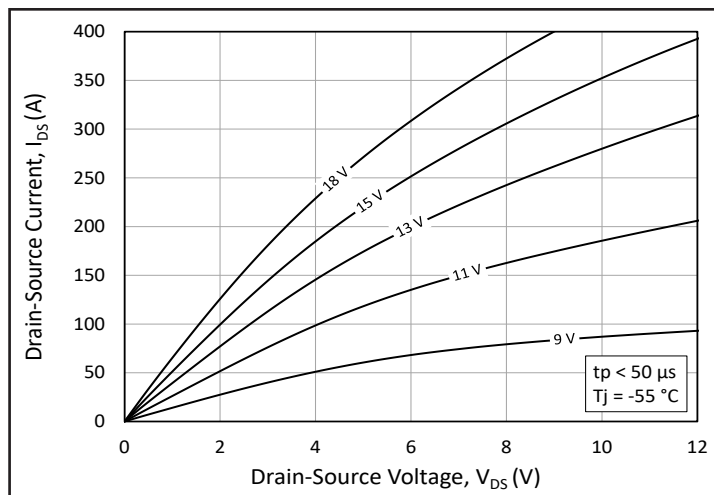


Figure 1. Output Characteristics $T_J = -55\text{ }^{\circ}\text{C}$

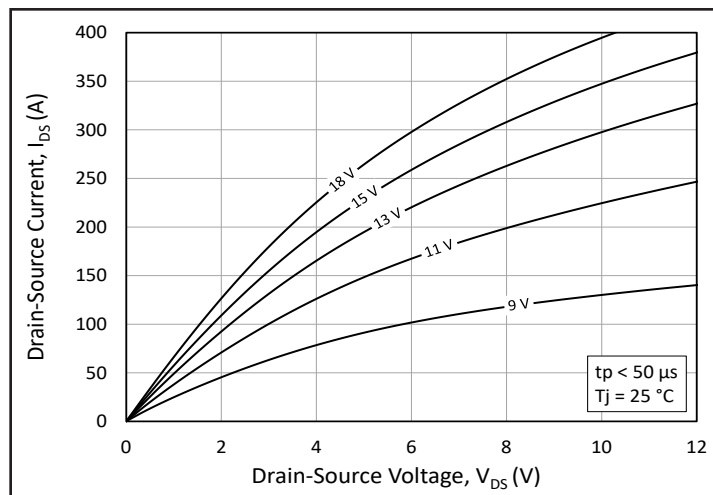


Figure 2. Output Characteristics $T_J = 25\text{ }^{\circ}\text{C}$

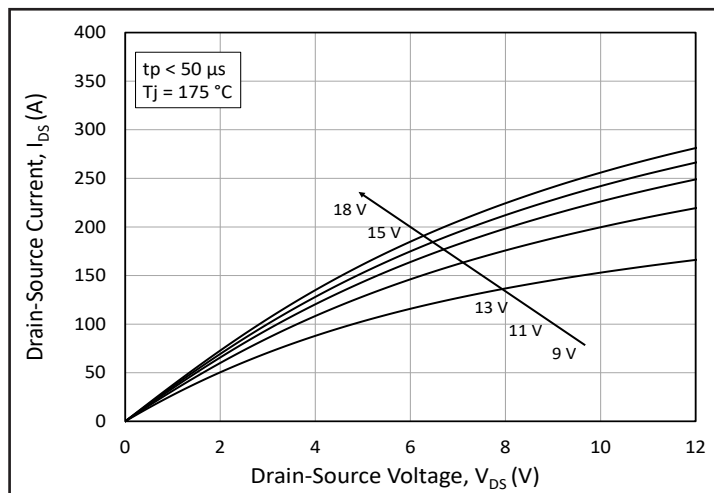


Figure 3. Output Characteristics $T_J = 175\text{ }^{\circ}\text{C}$

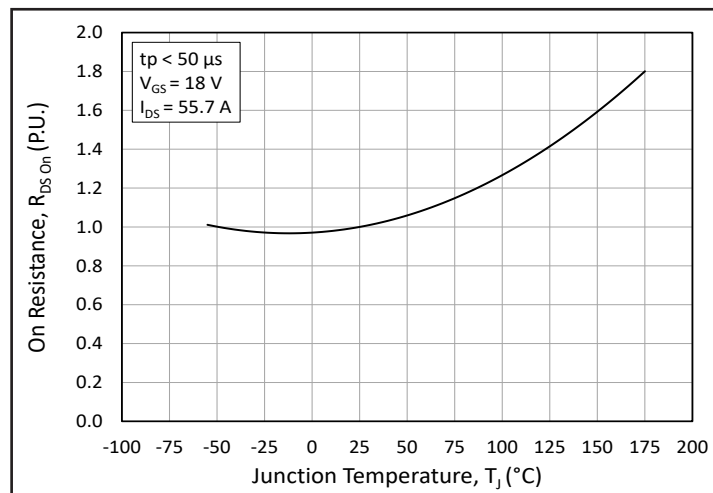


Figure 4. Normalized On-Resistance vs. Temperature

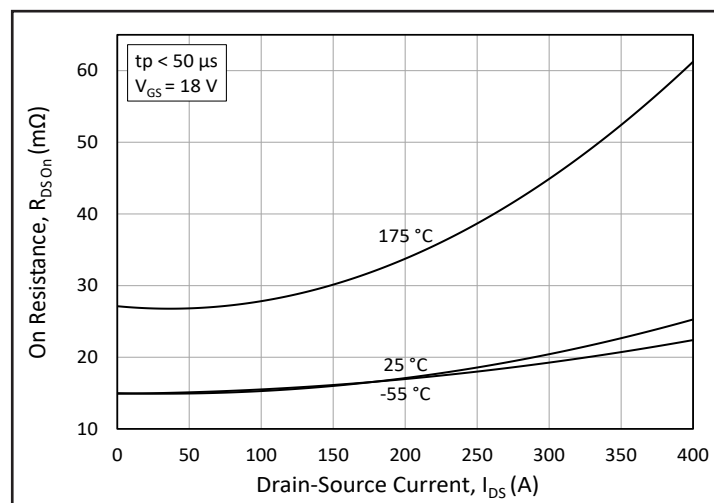


Figure 5. On-Resistance vs. Drain Current
For Various Temperatures

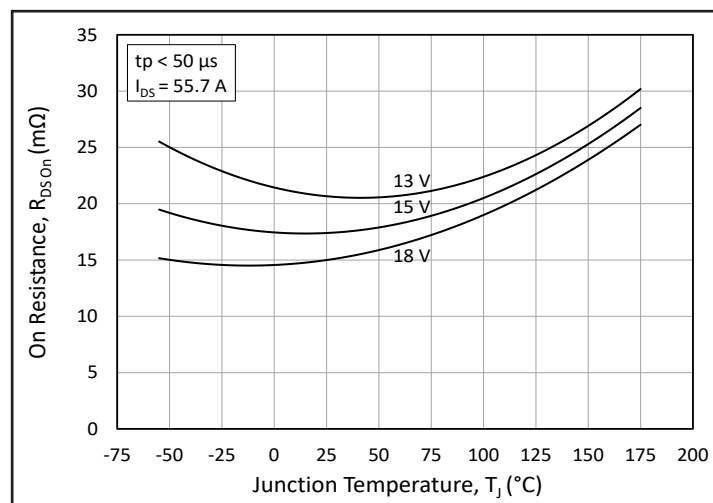


Figure 6. On-Resistance vs. Temperature
For Various Gate Voltage

Typical Performance

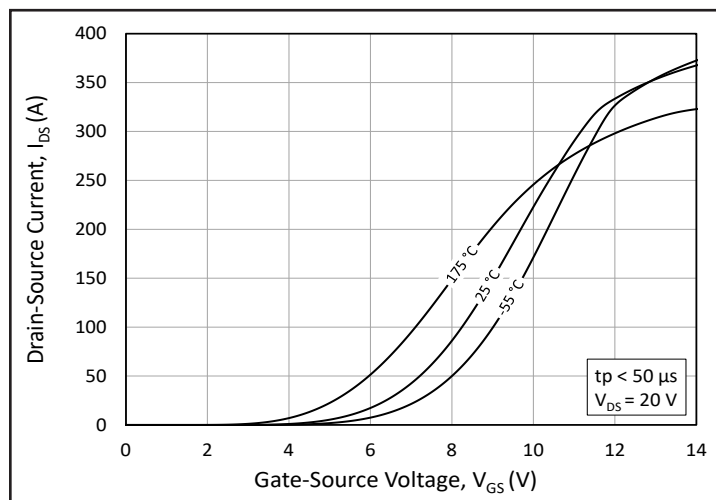


Figure 7. Transfer Characteristic for Various Junction Temperatures

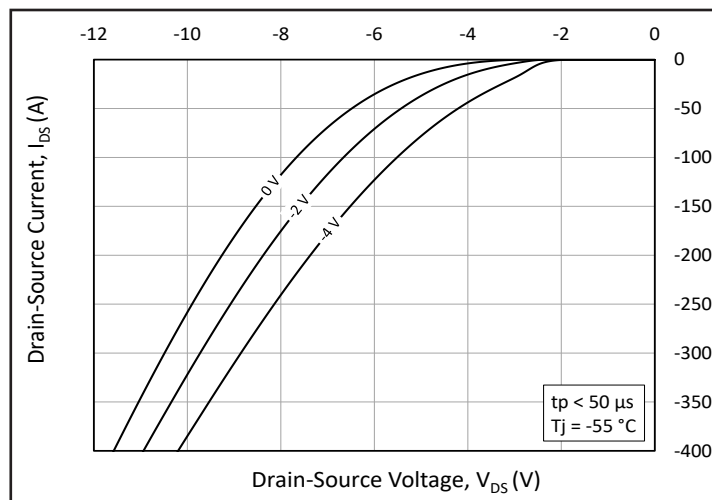


Figure 8. Body Diode Characteristic at -55 °C

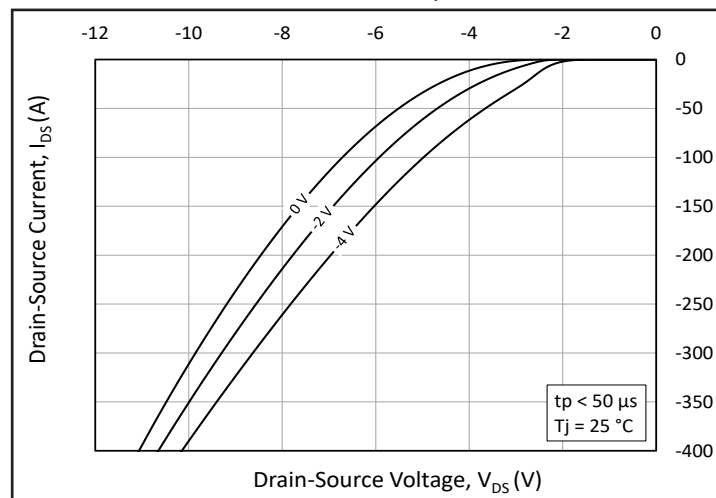


Figure 9. Body Diode Characteristic at 25 °C

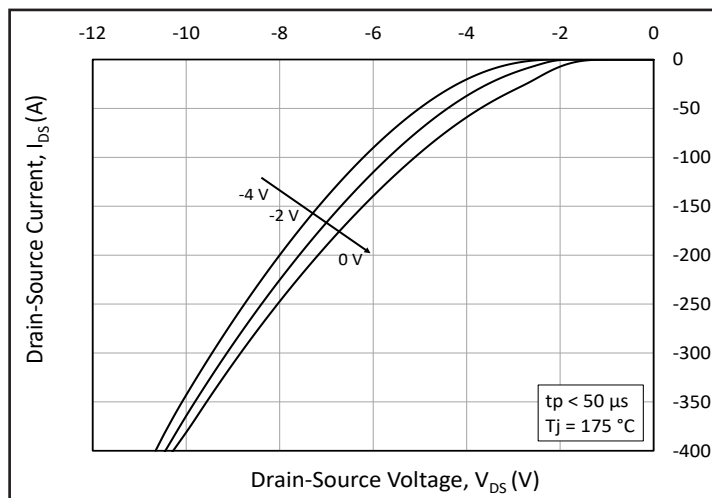


Figure 10. Body Diode Characteristic at 175 °C

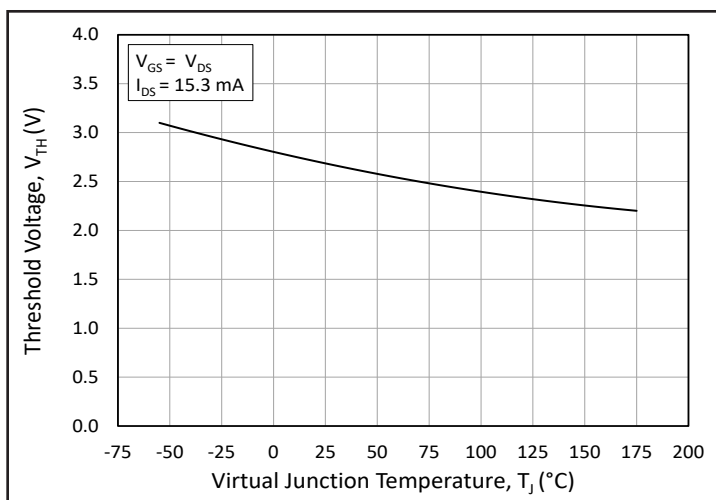


Figure 11. Threshold Voltage vs. Temperature

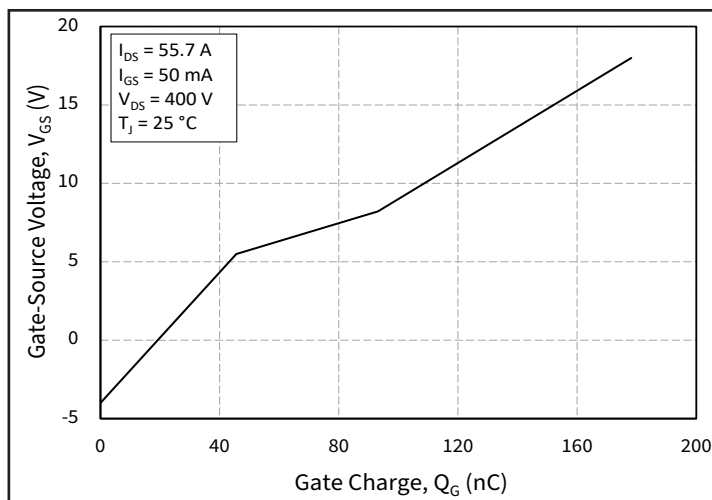


Figure 12. Gate Charge Characteristics

Typical Performance

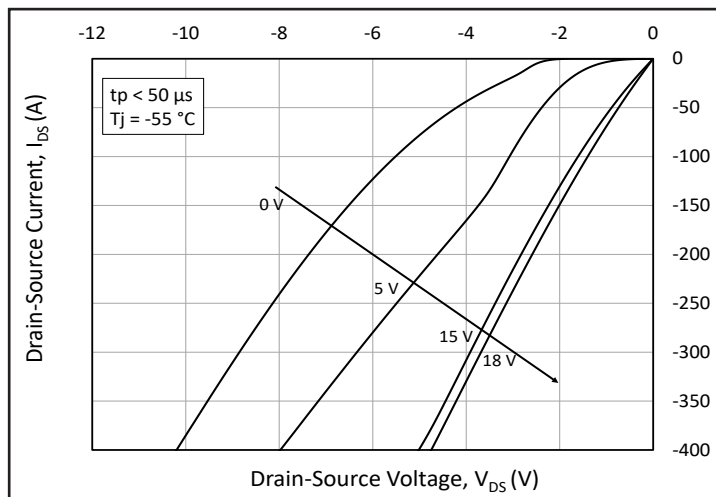


Figure 13. 3rd Quadrant Characteristic at -55 °C

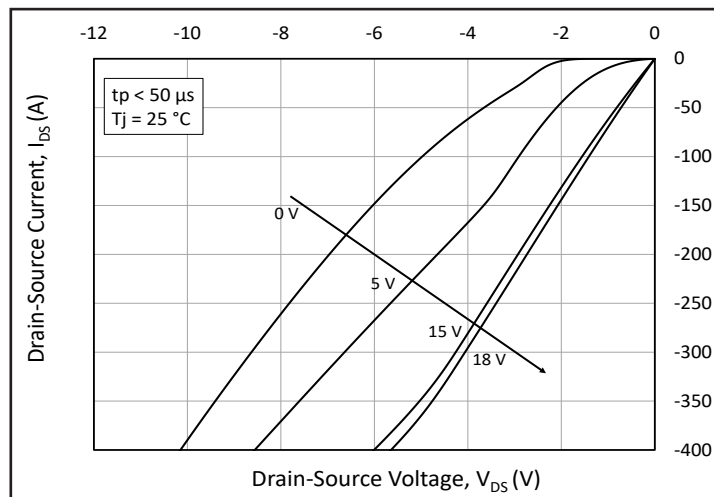


Figure 14. 3rd Quadrant Characteristic at 25 °C

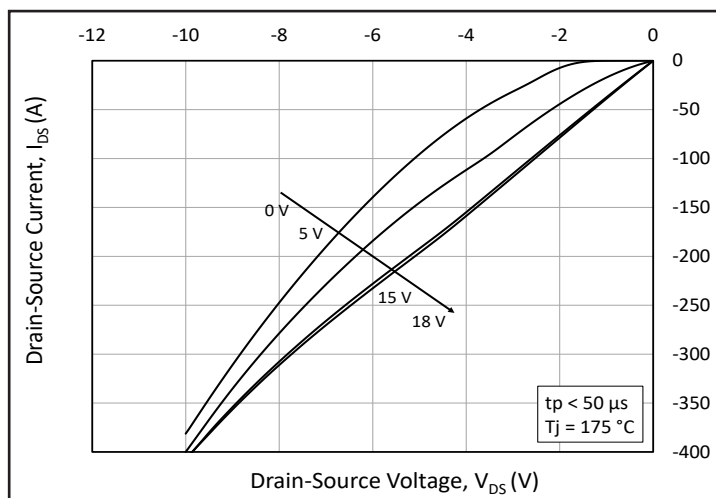


Figure 15. 3rd Quadrant Characteristic at 175 °C

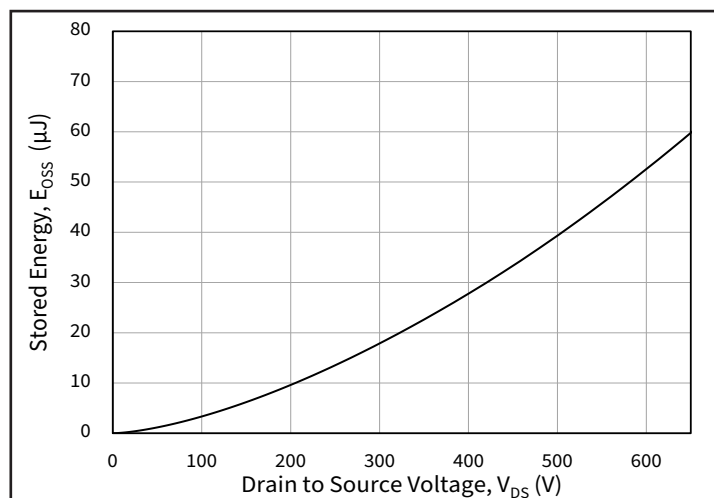


Figure 16. Output Capacitor Stored Energy

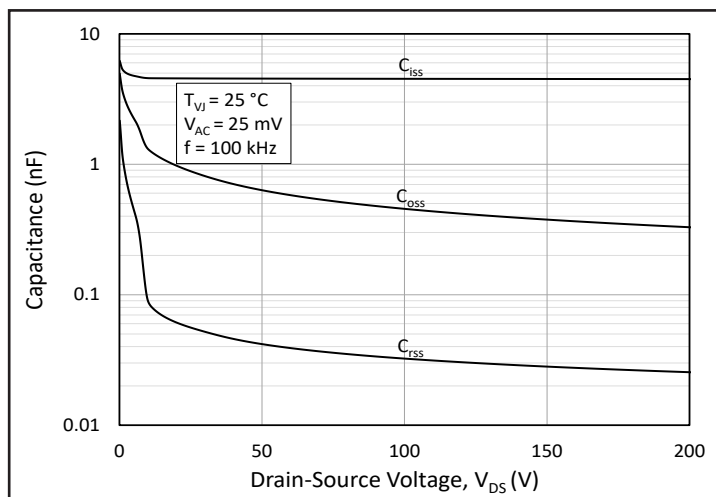


Figure 17. Capacitances vs. Drain-Source Voltage (0 - 200V)

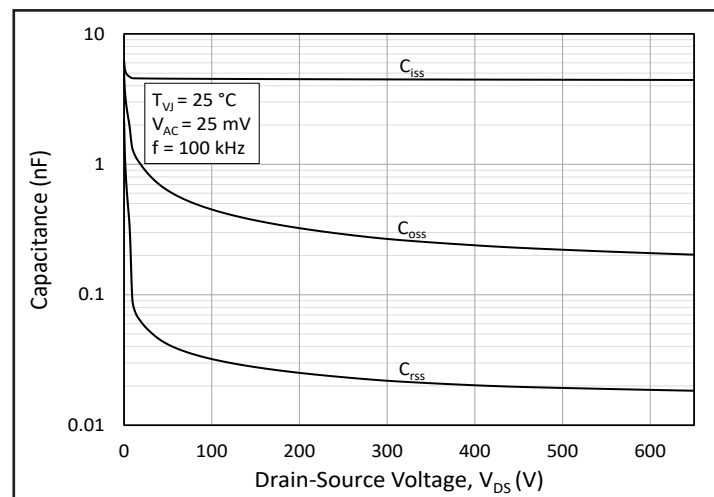


Figure 18. Capacitances vs. Drain-Source Voltage (0 - 650V)

Typical Performance

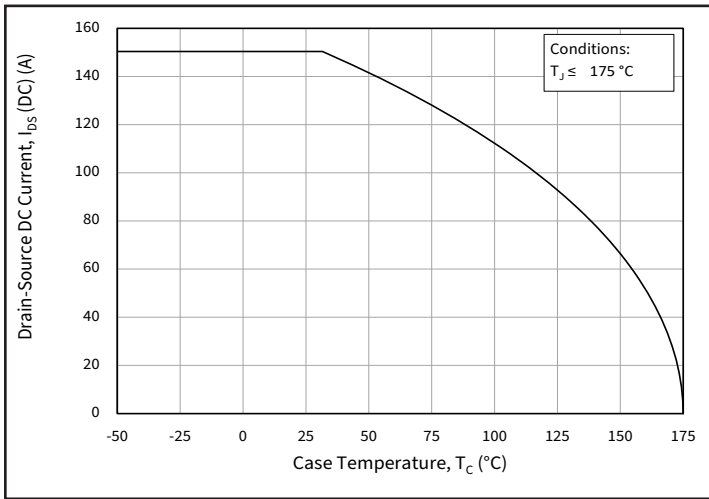


Figure 19. Continuous Drain Current Derating vs. Case Temperature

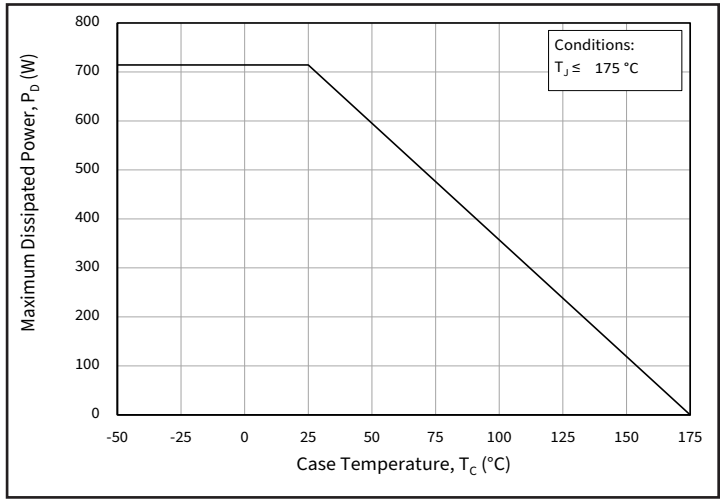


Figure 20. Maximum Power Dissipation Derating vs. Case Temperature

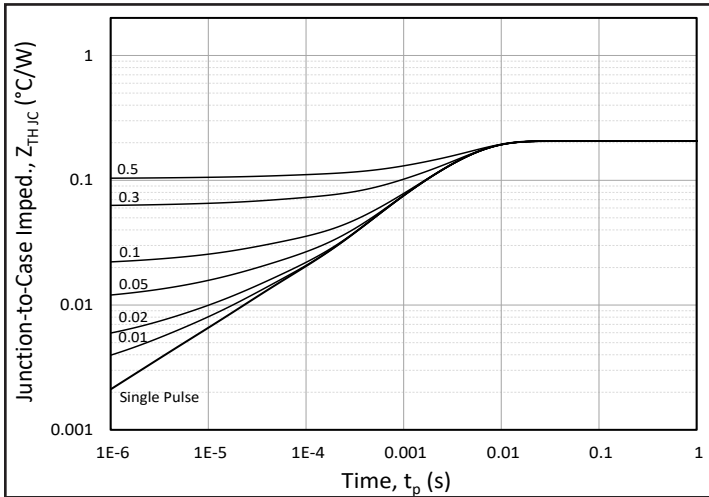


Figure 21. Transient Thermal Impedance (Junction - Case)

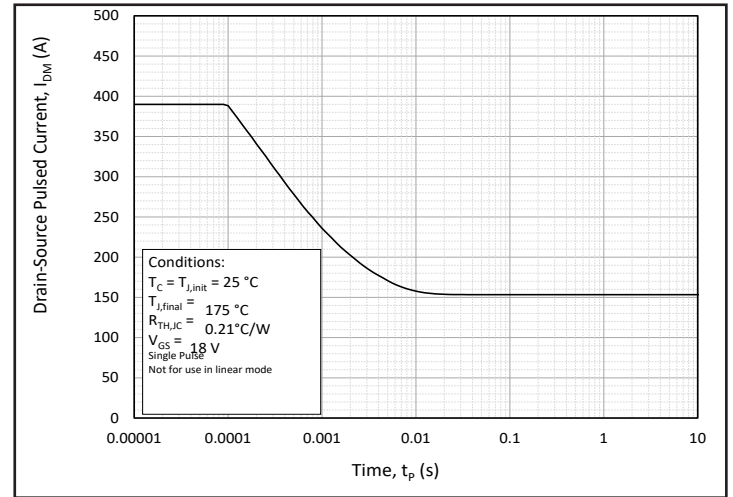


Figure 22. Safe Operating Area

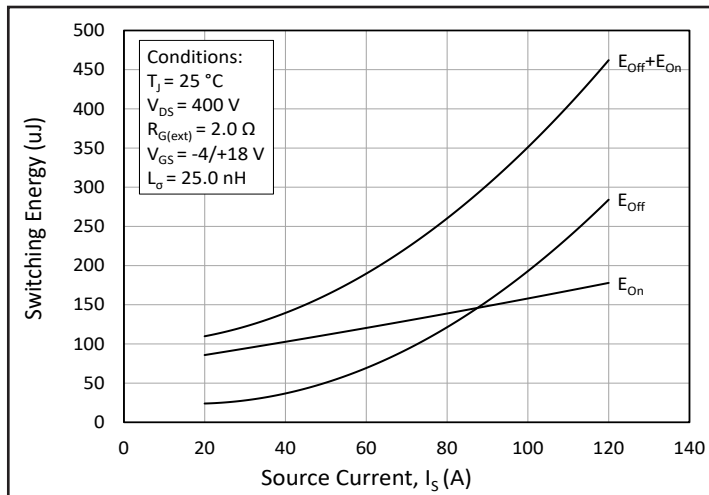


Figure 23. Clamped Inductive Switching Energy vs. Drain Current ($V_{DD} = 400V$)

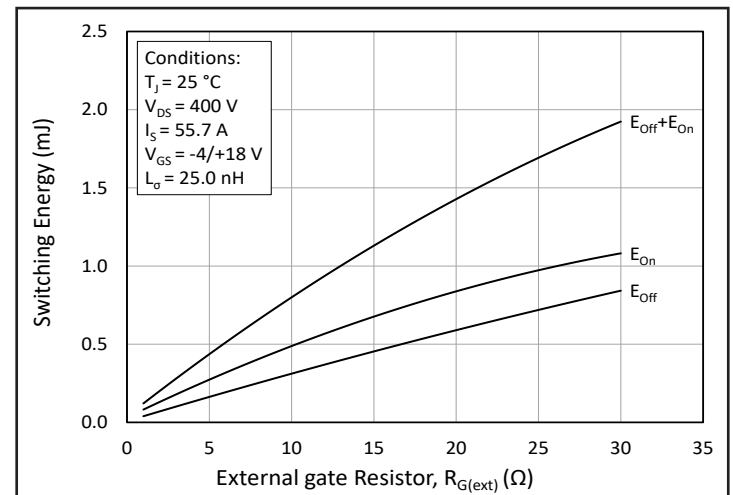


Figure 24. Clamped Inductive Switching Energy vs. $R_{G(ext)}$



Typical Performance

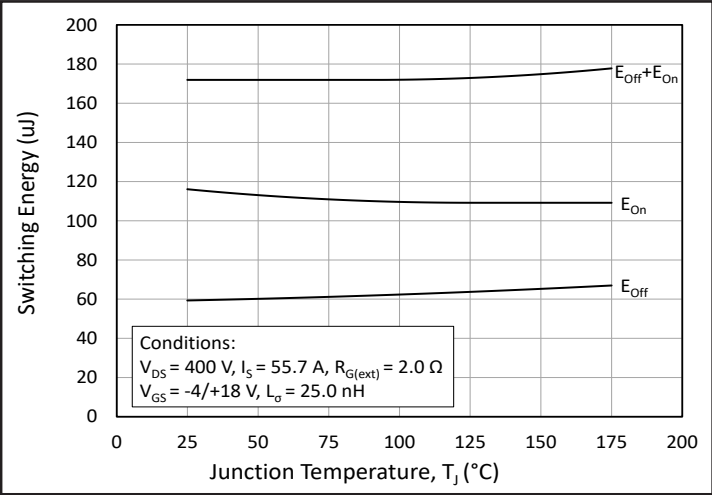


Figure 25. Clamped Inductive Switching Energy vs. Temperature

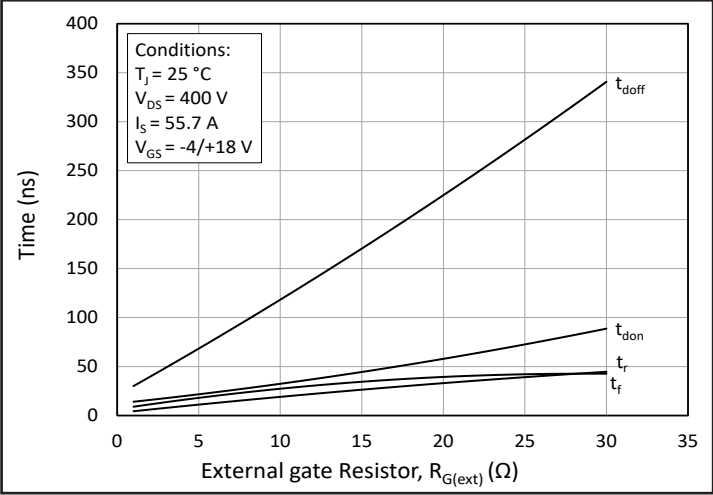


Figure 26. Switching Times vs. $R_{G(ext)}$

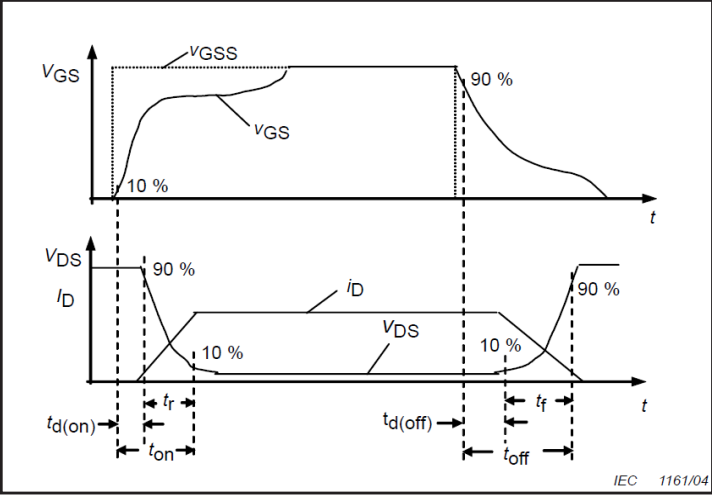


Figure 27. Switching Times Definition

Test Circuit Schematic

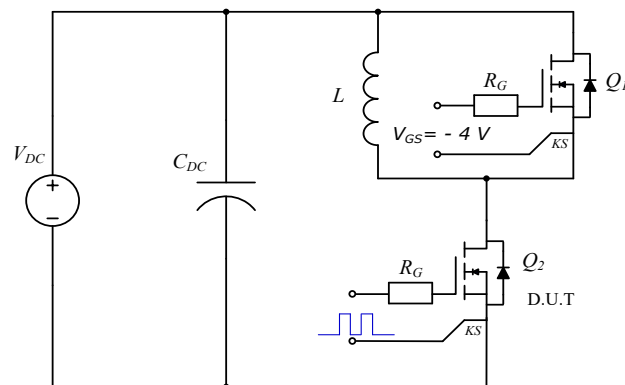
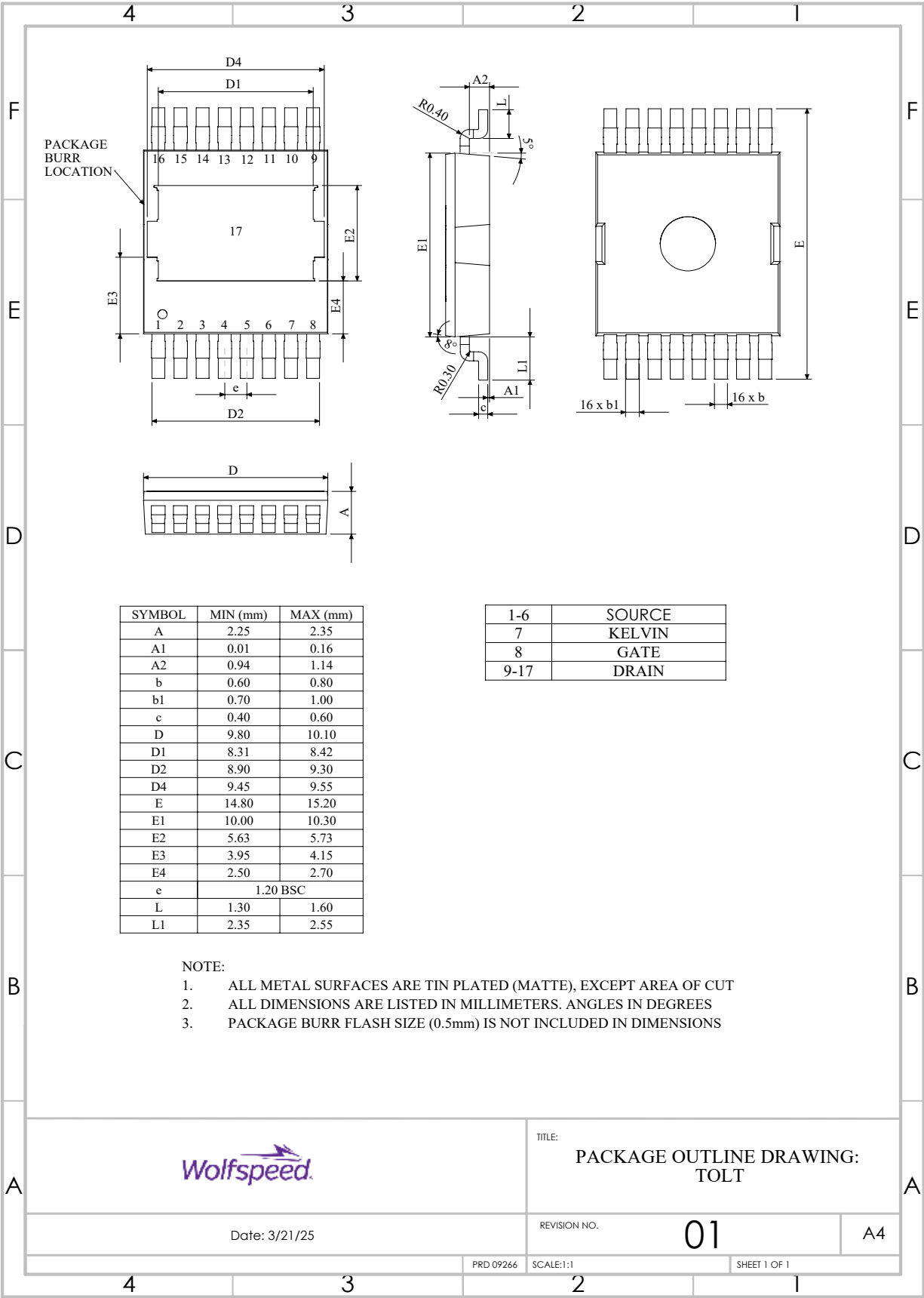


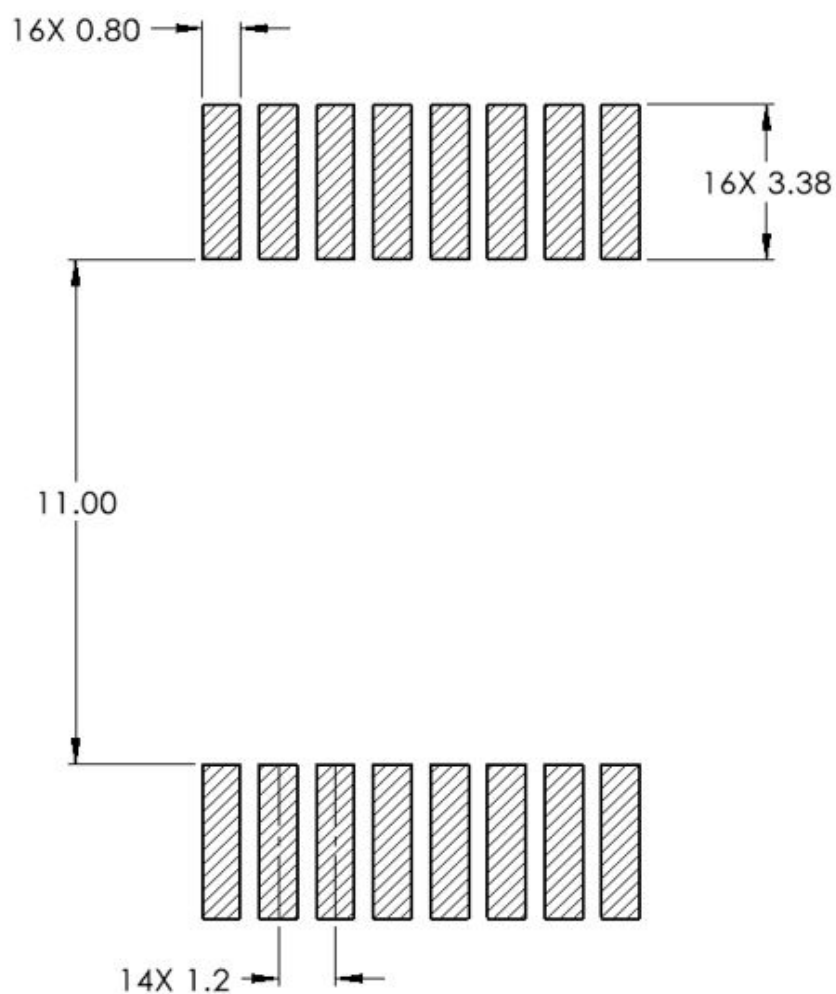
Figure 28. Clamped Inductive Switching
Waveform Test Circuit

Package Dimensions



**Recommended Solder Pad Layout**

All dimensions in mm





Revision history

Document Version	Date of release	Descriptiion of changes
1	November 2025	Initial release



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